

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE  
WASHINGTON, D.C. 20231

Inventor: **David Haas, et al.**

Serial No: **Div. of 09/826,718**

Filed: **April 4, 2001**

For: **Lasable Bond-Ply Materials  
for High Density Printed  
Wiring Boards**

Examiner:

Art Unit:

**PRELIMINARY AMENDMENT**

Mail Stop Patent Application  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir:

Please enter the following preliminary amendment:

**IN THE CLAIMS**

Please cancel all allowed claims (1-33) and add the following claims addressing subject matter in application serial number 09/826718:

34. A bond-ply material, comprising:

a cured core having a first surface and a second surface, wherein the core has a thickness of from about 5 microns to 200 microns and including from about 20% and 70% weight percent (wt%) non-woven reinforcement material selected from glass microfibers, organic fibers and mixtures hereof; and

wherein the material comprises a plurality of vias filled with an electrically conductive material or a conductor precursor.